

	U	1	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval Classif	Inventor
1	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 5629559 A	19970513	27	Package for semiconductor device	257/666	257/691; 257/692; 257/700		Miyahara, Kenichiro
2	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 5943557 A	19990824	6	Method and structure for attaching a semiconductor die to a lead frame	438/118	438/119; 438/123		Moden, Walter L.
3	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 6353268 B1	20020305	8	Semiconductor die attachment method and apparatus	257/796	257/673; 257/676; 257/783; 438/118		Cobbley, Chad A. et al.
4	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 5208188 A	19930504	12	Process for making a multilayer lead frame assembly for an integrated circuit structure and multilayer integrated circuit die package formed by such process	156/310	156/273.9; 257/668; 257/675; 438/118		Newman, Robert A.
5	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 5356949 A	19941018	10	Adhesive composition comprising (meth)acrylate polymer and epoxy resin	522/102	522/103; 522/109; 525/112		Komiyama, Mikio et al.